

AMENDMENT TO H.R. 5300
OFFERED BY MR. HUIZENGA OF MICHIGAN

At the appropriate place, insert the following:

1 **SEC. ____.** **ADDITIONAL RESPONSIBILITIES WITH REGARD**
2 **TO MULTILATERAL SEMICONDUCTOR SUP-**
3 **PLY CHAIN SECURITY COORDINATION.**

4 (a) DUTIES.—In addition to the responsibilities de-
5 scribed in this Act, the Under Secretary for International
6 Security Affairs, or a designee, shall maintain continuous
7 observation and coordination of engagement with govern-
8 ments of countries that maintain significant capabilities
9 in semiconductor technology, design, manufacturing, ma-
10 terials, and equipment subsystems to establish coordinated
11 approaches for protecting critical semiconductor tech-
12 nologies from acquisition and indigenous development by
13 foreign adversaries.

14 (b) COORDINATION OBJECTIVES.—The Under Sec-
15 retary shall use diplomatic engagement pursuant to sub-
16 section (a) to seek to achieve—

17 (1) alignment of restrictions regarding foreign
18 adversary access to advanced semiconductor manu-
19 facturing equipment, including lithography systems,
20 thermocompression bonding equipment, deposition

1 equipment, etching tools, inspection systems, and
2 their related subsystems and components;

3 (2) coordinated restrictions on semiconductor
4 design tools, intellectual property transfers, technical
5 assistance, and servicing that could enable indige-
6 nous semiconductor development capabilities of for-
7 eign adversaries;

8 (3) harmonized approaches to controlling dual-
9 use semiconductor materials, including photoresists,
10 specialty gases, and advanced substrates;

11 (4) joint monitoring and enforcement mecha-
12 nisms to prevent circumvention of semiconductor
13 technology controls through third-country entities;
14 and

15 (5) information sharing regarding semicon-
16 ductor technology transfer risks, end-user
17 verification, and supply chain security threats.

18 (c) ROUTINE ASSESSMENT.—

19 (1) ASSESSMENT.—The Under Secretary shall
20 regularly assess and determine the extent to which
21 countries engaged with pursuant to subsection (a)
22 are implementing security measures to advance
23 United States and United States partner country se-
24 curity and whether a country engaged with pursuant
25 to such subsection is not implementing adequate

1 measures to prevent semiconductor technology trans-
2 fer to foreign adversaries.

3 (2) NOTIFICATION.—If the Under Secretary de-
4 termines that a country engaged with pursuant to
5 subsection (a) is not implementing adequate security
6 measures to prevent semiconductor technology trans-
7 fer to foreign adversaries, the Under Secretary shall
8 notify the appropriate congressional committees of
9 such determination. The notification shall include—

10 (A) a detailed explanation of the specific
11 deficiencies in the country’s semiconductor tech-
12 nology protection measures; and

13 (B) efforts to prevent semiconductor tech-
14 nology transfer to foreign adversaries.

15 (3) CONGRESSIONAL BRIEFING.—Not later than
16 90 days after the date of enactment of this Act, and
17 every 180 days thereafter for 3 years, the Under
18 Secretary shall brief the appropriate congressional
19 committees on—

20 (A) the status of diplomatic engagement
21 with governments of countries that maintain
22 significant capabilities in semiconductor tech-
23 nology, design, manufacturing, materials, and
24 equipment subsystems;

1 (B) progress toward achieving the coordi-
2 nation objectives specified in subparagraph
3 (a)(1);

4 (C) any new determinations of inadequate
5 cooperation made under subsection (a)(2); and

6 (D) the effectiveness of multilateral coordi-
7 nation in preventing semiconductor technology
8 transfer to foreign adversaries.

9 (d) DEFINITIONS.—In this section:

10 (1) The term “foreign adversary” has the
11 meaning described in section 8(c)(2) of the Secure
12 and Trusted Communications Networks Act of 2019
13 (47 U.S.C. 1607(c)(2)).

14 (2) The term “semiconductor technology”
15 means—

16 (A) integrated circuits, microprocessors,
17 and memory devices;

18 (B) semiconductor manufacturing equip-
19 ment, tools, and related subsystems;

20 (C) semiconductor design software and in-
21 tellectual property;

22 (D) semiconductor materials and specialty
23 chemicals;

24 (E) testing, assembly, and packaging
25 equipment; and

1 (F) any technology, component, or service
2 that is essential to semiconductor design, manu-
3 facturing, or testing processes.

4 (e) SUNSET.—This section shall cease to be effective
5 on the date that is 5 years after the date of enactment
6 of this Act.

